

# xLED-LUN-4568 Pin Fin LED Heat Sink Φ45mm for Luminus

## **Features VS Benefits**

- \* The xLED-LUN-4568 Luminus Pin Fin LED Heat Sinks are specifically designed for
- luminaires using the Luminus LED engines.
- \* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- \* For spotlight and downlight designs from 300 to 1,400 lumen.
- \* Thermal resistance range Rth 4.76°C/W.
- \* Modular design with mounting holes foreseen for direct mounting of Luminus COB series.
- \* Diameter 45mm standard height 68mm, Other heights on request.
- \* Forged from highly conductive aluminum.

### Zhaga LED engine and radiator assembly is a unified future international standardization

- \* Below you find an overview of Luminus COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- \* In this way mechanical after work and related costs can be avoided, and lighting designers
- can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.

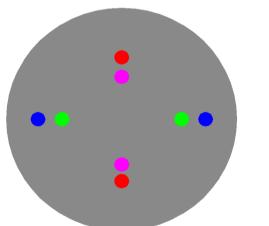












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#### Luminus COB series. CXM-6-AC; CIM/ CLM/CXM-9 -AC; With the Zhaga Book 11 holders for the green indicator mark TE Connectivity Holder: 2213678-5;

Luminus LED Modules directly Mounting Options

BJB Holder:47.319.6060.50; Without the holders for the pink indicator marks. Direct mounting with machine screws M3x6.5mm. With the LEDiL products: Lena series: CN14xxx; C12xxx;

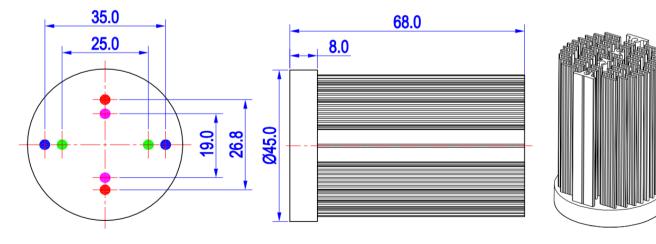
#### Luminus COB series.

CXM-11-AC; CIM/CLM/CXM-14; With the Zhaga Book 3 holders for the blue indicator marks. TE Connectivity Holder: 2213254-1; BJB Holder:47.319.2021.50; Without the holders for the red indicator marks. Direct mounting with machine screws M3x6.5mm. With the LEDiL products: Lena series: CN12xxx; C12xxx;





OPTION			Lenina Series	Lena series		DEPIR	DISTANCE
1	CXM-6-AC; CIM/ CLM/CXM-9 -AC;	/	CN14xxx; C12xxx;	CN14xxx; C12xxx;	M3	6.5mm	19.0mm/ 2-@180°
2		BJB Holder 47.319.6060.50			M3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
		TE Holder 2213678-5					
3	CXM-11; CIM/CLM/CXM-14	/	CN12xxx; C12xxx;	CN12xxx;	M3	6.5mm	26.8mm/ 2-@180°
4		BJB Holder 47.319.2021.50			M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
		TE Holder 2213254-1					



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## The product deta table

xLED	Model No.	xLED-LUN-4568	
an classes	Heatsink Size	Φ45xH68mm	
	Heatsink Material	AL1070	
	Finish	Black Anodized	
	Weight (g)	90.0	
	Dissipated power (Ths-amb,50℃)	10.5 (W)	
	Cooling surface area (mm²)	49775	
	Thermal Resistance (Rhs-amb)	4.76 (°C/W)	

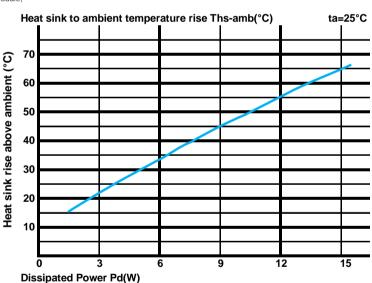
## The thermal data table

\* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

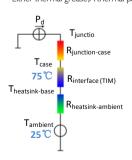
\*To calculate the dissipated power please use the following formula:  $Pd = Pe \times (I - \eta L)$ .

Pd - Dissipated power ; Pe - Electrical power ;  $\eta L =$  Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)	
		xLED-LUN-4568		
Dissipated Power Pd(W)	3.0	7.00	21.0	
	6.0	5.50	33.0	
	9.0	5.00	45.0	
	12.0	4.58	55.0	
	15.0	4.27	64.0	



\*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material). MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



\*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (Ths - Ta)/Pd$ 

 $\theta\,$  - Thermal Resistance [°C/W] ;  $\,$  Ths - Heatsink temperature ;  $\,$  Ta - Ambient temperature ;

\*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is  $R_{\text{junction-case}}$ , the thermal resistance of the TIM outside the package is  $R_{\text{interface (TIM)}}$  [°C/W], the thermal resistance with the heat sink is  $R_{\text{heatsink-ambert}}$  [°C/W], and the ambient temperature is  $T_{\text{ambert}}$  [°C].

\*Thermal resistances outside the package  $R_{interface (TIM)}$  and  $R_{heatsink-ambient}$  can be integrated into the thermal resistance  $R_{case-ambient}$  at this point. Thus, the following formula is also used:  $T_{junction}=(R_{junction-case}+R_{case-ambient})$ Pd+ $T_{ambient}$ 

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